

CONFIDENTIAL



UNIVERSITI TUN HUSSEIN ONN MALAYSIA

**FINAL EXAMINATION
SEMESTER II
SESSION 2018/2019**

COURSE NAME : ADVANCED SEMICONDUCTOR DEVICES
COURSE CODE : BED 41003
PROGRAMME : BEJ
EXAMINATION DATE : JUNE / JULY 2019
DURATION : 3 HOURS
INSTRUCTION : ANSWER ALL QUESTIONS

THIS QUESTION PAPER CONSISTS OF TEN (10) PAGES

CONFIDENTIAL

TERBUKA

- Q1** (a) Explain the importance of electron diffusion process during BJT operation. (3 marks)
- (b) Determine the emitter injection efficiency, γ , given emitter concentration, N_E , is 1000 times higher than base concentration, N_B , emitter diffusion, D_E , is quadruple compared to base diffusion, D_B , and emitter width, x_E , is double than base width, x_B . (5 marks)
- (c) Analyse how the recombination process affect the output current of BJT. (3 marks)
- (d) Analyse the change in collector current, i_C , if the base width, x_B , is halved and base-emitter junction area, A_{BE} , is increased by 20%. Express the change in percentage and assume all other parameters are unchanged. (4 marks)
- Q2** (a) Explain the main factor that causes space-charge effect in an IMPATT diode. (3 marks)
- (b) Referring to **Figure Q2(b)**, calculate the maximum electric field, E_m , and breakdown voltage, V_B , for a Si 2-sided IMPATT diode for concentration $N = 2 \times 10^{15} \text{ cm}^{-3}$. (5 marks)
- (c) Analyse the reason carrier ionisation occurs close to p-n junction in IMPATT diode (4 marks)
- (d) Analyse main factors that cause the depletion region covers the whole middle layers in an IMPATT diode. (4 marks)
- Q3** (a) Explain the change in energy band diagram of semiconductor material forming Schottky barrier when being applied with reverse bias. (3 marks)
- (b) Suppose a Schottky barrier is formed between Ge and Ti. Calculate the depletion region width, x_n , created in the Ge layer doped to $N_d = 10^{16} \text{ cm}^{-3}$ at $T = 300 \text{ K}$. Next, determine the maximum electric field in the Ge layer. Assume $\chi_{Ge} = 4.13 \text{ V}$. (10 marks)
- (c) Suppose a Schottky barrier is formed between a metal and a semiconductor with the condition of $\phi_m > \phi_s$. Analyse a solution to change this Schottky barrier to become an ohmic contact without changing the semiconductor material. (5 marks)
- (d) Analyse the appropriate expression of relative change in the contact resistance, R_C , if the semiconductor layer in an ohmic contact is changed from Ge to Si. Assume the doping concentration is similar for both semiconductor materials. (5 marks)

- Q4** (a) Explain the usefulness of forming ohmic contact at gate terminal in a MESFET. (3 marks)

- (b) Suppose a Si JFET at $T = 300\text{ K}$ has the following parameters:

$$N_a = 10^{17}\text{ cm}^{-3}, N_d = 10^{14}\text{ cm}^{-3}, a = 1.25\text{ }\mu\text{m}, L = 15\text{ }\mu\text{m}, W = 60\text{ }\mu\text{m}, \text{ and}$$

$$\mu_n = 1000\frac{\text{cm}^2}{\text{V}\cdot\text{s}}$$

Determine the internal pinch off voltage, V_{p0} , built-in potential, V_{bi} , and pinch off current, I_p , for this transistor.

(10 marks)

- (c) Analyse the importance of n^+ contact layer coincides with the undoped GaAs layer in MODFET structure as shown in **Figure Q4(c)**.

(5 marks)

- (d) Using the appropriate formula, analyse the effect of metal work function, ϕ_m , to the saturation drain voltage, V_{Dsat} , in MESFET.

(5 marks)

- Q5** (a) Explain **ONE (1)** purpose of having low doping concentration of n_1 layer in a thyristor. (3 marks)

- (b) Calculate the anode current, I_A , cathode current, I_K , and internal base current, I_{B1} , when a thyristor is in forward blocking mode given the following parameters:

$$\alpha_1 = 0.455, \alpha_2 = 0.403, I_{CO1} = 54\text{ }\mu\text{A}, I_{CO2} = 90\text{ }\mu\text{A}, \text{ and } I_g = 1\text{ mA}$$

Next, determine gate current, I_g , and I_{B1} needed to maintain I_A if I_{CO1} and I_{CO2} increases 20% and 30% respectively. Assume both current gains are unchanged.

(10 marks)

- (c) Analyse the essential parameter that determines which breakdown mechanism that occur in the thyristor.

(4 marks)

- (d) Analyse the required condition to prevent the thyristor entering forward conduction mode using the two-transistor model.

(6 marks)

- END OF QUESTIONS -

FINAL EXAMINATION

SEMESTER/SESSION : SEM II / 2018/2019
 COURSE NAME : ADVANCED SEMICONDUCTOR DEVICES

PROGRAMME : BEJ
 COURSE CODE : BED 41003

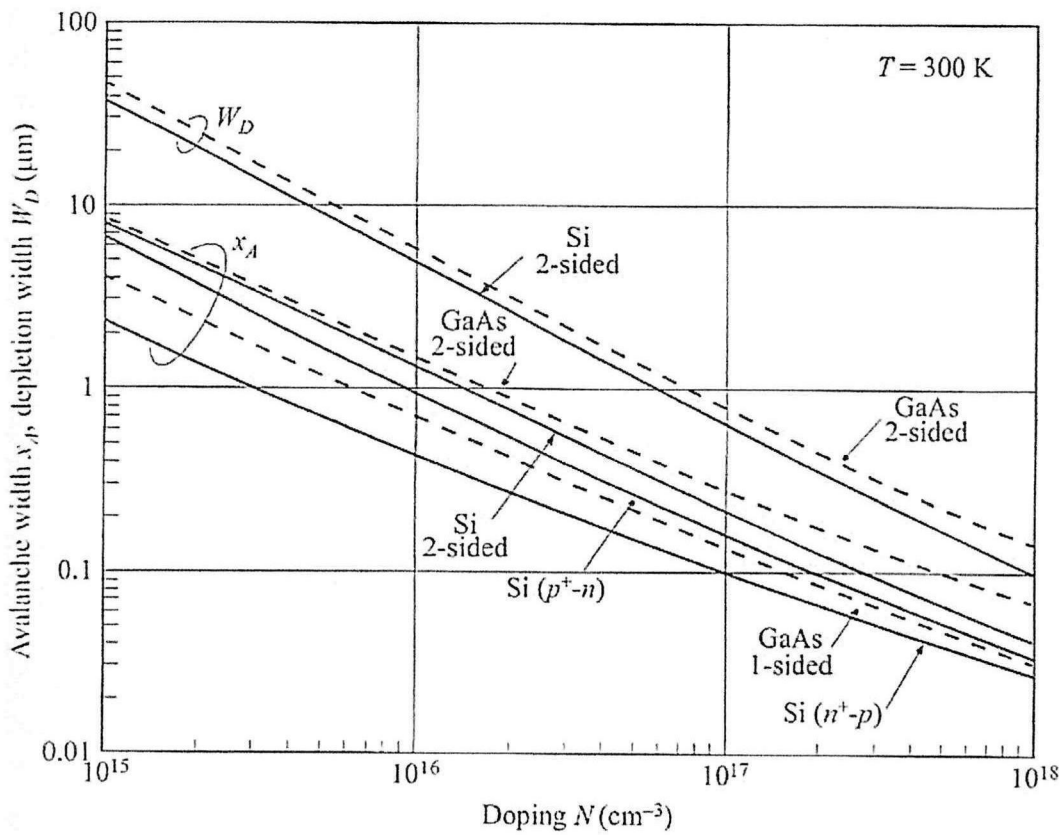


Figure Q2(b)

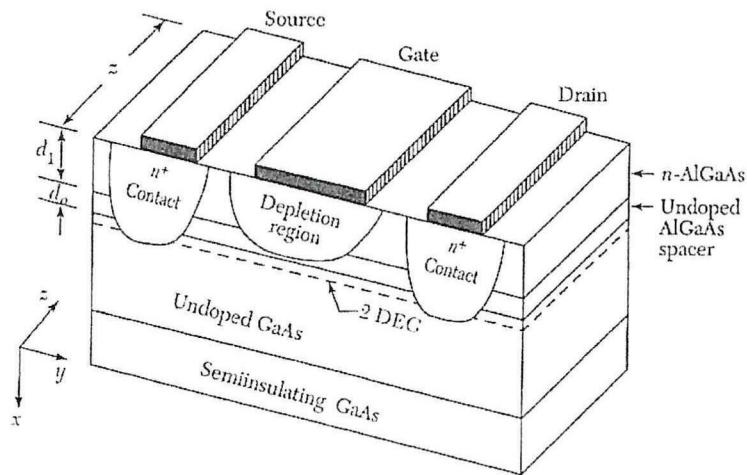


Figure Q4(c)

TERBUKA

FINAL EXAMINATION

SEMESTER/SESSION : SEM II / 2018/2019
 COURSE NAME : ADVANCED SEMICONDUCTOR DEVICES
 PROGRAMME : BEJ
 COURSE CODE : BED 41003

Table 1
Physical constants

Boltzmann's constant	$k = 1.38 \times 10^{-23} \text{ J/K}$ $= 8.62 \times 10^{-5} \text{ eV/K}$
Electronic charge (magnitude)	$q = 1.6 \times 10^{-19} \text{ C}$
Free electron rest mass	$m_0 = 9.11 \times 10^{-31} \text{ kg}$
Permeability of free space	$\mu_0 = 4\pi \times 10^{-7} \text{ H/m}$
Permittivity of free space	$\epsilon_0 = 8.85 \times 10^{-14} \text{ F/cm}$ $= 8.85 \times 10^{-12} \text{ F/m}$
Planck's constant	$h = 6.625 \times 10^{-34} \text{ J-s}$ $= 4.135 \times 10^{-15} \text{ eV-s}$
Modified Planck's constant	$\hbar = 1.054 \times 10^{-34} \text{ J-s}$
Proton rest mass	$M = 1.67 \times 10^{-27} \text{ kg}$
Speed of light in vacuum	$c = 2.98 \times 10^{10} \text{ cm/s}$
Thermal voltage ($T = 300 \text{ K}$)	$V_t = kT/q = 0.0259 \text{ V}$

Table 2
Work function of selected metals

Metal	Work function (V)
Silver (Ag)	4.26
Aluminum (Al)	4.28
Gold (Au)	5.10
Titanium (Ti)	4.33
Tungsten (W)	4.55

FINAL EXAMINATION

SEMESTER/SESSION : SEM II / 2018/2019

PROGRAMME : BEJ

COURSE NAME : ADVANCED SEMICONDUCTOR DEVICES

COURSE CODE : BED 41003

Table 3
Silicon, Gallium Arsenide and Germanium properties ($T = 300\text{ K}$)

Property	Si	GaAs	Ge
Atoms (cm^{-3})	5.0×10^{22}	4.42×10^{22}	4.42×10^{22}
Atomic weight	28.09	144.63	72.60
Density (g/cm^{-3})	2.33	5.32	5.33
Lattice constant (\AA)	5.43	5.65	5.65
Melting point ($^{\circ}\text{C}$)	1415	1238	937
Dielectric constant	11.7	13.1	16.0
Bandgap energy (eV)	1.12	1.42	0.66
Electron affinity, χ (volts)	4.01	4.07	4.13
Effective density of states in conduction band, N_c (cm^{-3})	2.8×10^{19}	4.7×10^{17}	1.04×10^{19}
Effective density of states in valence band, N_v (cm^{-3})	1.04×10^{19}	7.0×10^{18}	6.0×10^{18}
Intrinsic carrier concentration (cm^{-3})	1.5×10^{10}	1.8×10^6	2.4×10^{13}
Mobility ($\text{cm}^2/\text{V-s}$)			
Electron, μ_n	1350	8500	3900
Hole, μ_p	480	400	1900
Effective mass (density of states)			
Electrons ($\frac{m_n^*}{m_0}$)	1.08	0.067	0.55
Holes ($\frac{m_p^*}{m_0}$)	0.56	0.48	0.37

FINAL EXAMINATION

SEMESTER/SESSION : SEM II / 2018/2019 PROGRAMME : BEJ
 COURSE NAME : ADVANCED SEMICONDUCTOR DEVICES COURSE CODE : BED 41003

Table 4
List of formula

Bipolar Transistors

- | | |
|--|--|
| 1. $i_C = eD_n A_{BE} \frac{dn_x}{dx} = -\frac{eD_n A_{BE}}{x_B} \cdot n_{B0} \exp\left(\frac{v_{BE}}{V_t}\right)$ | 2. $i_C = I_S \exp\left(\frac{v_{BE}}{V_t}\right)$ |
| 3. $i_{E2} = I_{S2} \exp\left(\frac{v_{BE}}{V_t}\right)$ | 4. $i_E = i_{E1} + i_{E2} = I_{SE} \exp\left(\frac{v_{BE}}{V_t}\right)$ |
| 5. $\frac{i_C}{i_E} = \alpha$ | 6. $\frac{i_C}{i_B} = \beta$ |
| 7. $V_{CC} = I_C R_C + V_{CB} + V_{BE} = V_R + V_{CE}$ | 8. $V_{CE} = V_{CC} - I_C R_C$ |
| 9. $\alpha_0 = \frac{J_C}{J_E} = \frac{J_{nC} + J_G + J_{pC0}}{J_{nE} + J_R + J_{pE}}$ | 10. $\alpha = \frac{\partial J_C}{\partial J_E} = \frac{J_{nC}}{J_{nE} + J_R + J_{pE}}$ |
| 11. $\alpha = \gamma \alpha_T \delta$ | 12. $\gamma \approx \frac{1}{1 + \frac{N_B}{N_E} \cdot \frac{D_E}{D_B} \cdot \frac{x_B}{x_E}}$ |
| 13. $\alpha_T \approx \frac{1}{1 + \frac{1}{2} \left(\frac{x_B}{L_B}\right)^2}$ | 14. $\delta = \frac{1}{1 + \frac{J_{r0}}{J_{s0}} \exp\left(-\frac{eV_{BE}}{2kT}\right)}$ |
| 15. $I_C = g_0(V_{CE} + V_A)$ | 16. $p_p(0) = p_{p0} = N_A$ |
| 17. $n_p(0) = n_{p0} \exp\left(\frac{eV_{BE}}{kT}\right)$ | 18. $p_p(0)n_p(0) = p_{p0}n_{p0} \exp\left(\frac{eV_{BE}}{kT}\right)$ |

Microwave Diodes

- | | |
|---|--|
| 19. $V_B = \frac{1}{2} E_m W_D = \frac{\epsilon_s E_m^2}{2qN} \dots (1\text{-sided})$ | 20. $V_B = \frac{1}{2} E_m W_D = \frac{\epsilon_s E_m^2}{qN} \dots (2\text{-sided})$ |
| 21. $V_B = E_m W_D - \frac{qN_1 b}{\epsilon_s} \left(W_D - \frac{b}{2}\right) \dots (read)$ | 22. $V_B = \frac{E_m b}{2} + \frac{qN_2 W_D (W_D - b)}{2\epsilon_s} \dots (hi-lo)$ |
| 22. $V_B = E_m b + \left(E_m - \frac{qQ}{\epsilon_s}\right) (W_D - b) \dots (Ihil)$ | 24. $\int_0^{x_1} \langle \alpha \rangle dx = 0.95$ |
| 25. $E_{\min} = E_m - \frac{q[N_1 b + N_2 (W_D - b)]}{\epsilon_s}$ | 26. $I = Aq \Delta n v_s$ |
| 27. $R_{SC} = \frac{(W_D - x_A)^2}{2A \epsilon_s v_s}$ | 28. $J_m = \frac{E_m \epsilon_s v_s}{W_D}$ |
| 29. $V_m = E_m W_D$ | 30. $P_m = V_m J_m = E_m^2 \epsilon_s v_s$ |

FINAL EXAMINATION

SEMESTER/SESSION : SEM II / 2018/2019
 COURSE NAME : ADVANCED SEMICONDUCTOR DEVICES

PROGRAMME : BEJ
 COURSE CODE : BED 41003

Table 4
List of formula (Cont..)

Schottky barrier

31. $q\phi_{Bn0} = q(\phi_m - \chi)$

33. $q\psi_{bi} = q(\phi_{Bn0} - \phi_n)$

35. $|E_{\max}| = \frac{qN_D x_n}{\epsilon_s}$

37. $J = \left[A^* T^2 \exp\left(-\frac{e\phi_{Bn0}}{kT}\right) \right] \left[\exp\left(\frac{eV_F}{kT}\right) - 1 \right]$

39. $Q_{ss} = -qD_n (E_g - q\phi_0 - q\phi_{Bn0})$

41. $Q_{sc} = \sqrt{2q\epsilon_s N_D \left(\phi_{Bn0} - \phi_n - \frac{kT}{q} \right)}$

32. $q\phi_{Bp0} = E_g - q(\phi_m - \chi)$

34. $Q_{sc} = qN_D W_D = \sqrt{2q\epsilon_s N_D \psi_{bi}}$

36. $x_n = \sqrt{\frac{2\epsilon_s \psi_{bi}}{qN_D}}$

38. $J = J_{sT} \left[\exp\left(\frac{eV_F}{kT}\right) - 1 \right]$

40. $Q_M = -(Q_{ss} + Q_{sc})$

42. $\Delta = \phi_m - (\chi + \phi_{Bn0}) = -\frac{\delta Q_M}{\epsilon_i}$

Ohmic contact

43. $\phi_{Bn} = \phi_n$

45. $E_{00} = \frac{e\hbar}{2} \sqrt{\frac{N_d}{\epsilon_s m_n^*}}$

47. $R_C = \frac{\left(\frac{kT}{q}\right) \exp\left(\frac{q\phi_{Bn}}{kT}\right)}{A^* T^2}$

44. $J_i \propto \exp\left(-\frac{q\phi_{Bn}}{E_{00}}\right)$

46. $R_C = \frac{k}{A^* T q} \exp\left(\frac{q\phi_{Bn}}{kT}\right)$

48. $R = \frac{R_C}{A}$

Heterojunction

49. $\psi_{bi} = |\phi_{m1} - \phi_{m2}|$

51. $W_{D2} = \sqrt{\frac{2N_1 \epsilon_{s1} \epsilon_{s2} (\psi_{bi} - V)}{qN_2 (\epsilon_{s1} N_1 + \epsilon_{s2} N_2)}}$

52. $J_n = \frac{qD_{n2} n_{i2}^2}{L_{n2} N_2} \left[\exp\left(\frac{qV}{kT}\right) - 1 \right]$

55. $\frac{J_n}{J_p} \approx \frac{N_1}{N_2} \exp\left(-\frac{\Delta E_g}{kT}\right)$

50. $W_{D1} = \sqrt{\frac{2N_2 \epsilon_{s1} \epsilon_{s2} (\psi_{bi} - V)}{qN_1 (\epsilon_{s1} N_1 + \epsilon_{s2} N_2)}}$

52. $C_D = \sqrt{\frac{qN_1 N_2 \epsilon_{s1} \epsilon_{s2}}{2(\epsilon_{s1} N_1 + \epsilon_{s2} N_2) (\psi_{bi} - V)}}$

54. $J_p = \frac{qD_{p1} n_{i1}^2}{L_{p1} N_1} \left[\exp\left(\frac{qV}{kT}\right) - 1 \right]$

56. $J = qN_{D2} \sqrt{\frac{kT}{2\pi m_n^*}} \exp\left(\frac{q\psi_{b2}}{kT}\right) \left[\exp\left(\frac{qV_2}{kT}\right) - \exp\left(-\frac{qV_1}{kT}\right) \right]$

FINAL EXAMINATION

SEMESTER/SESSION : SEM II / 2018/2019
 COURSE NAME : ADVANCED SEMICONDUCTOR DEVICES

PROGRAMME : BEJ
 COURSE CODE : BED 41003

Table 4
List of formula (Cont..)

JFET

$$57. \quad h = \sqrt{\frac{2\epsilon_s(V_{bi} + V_{DS} - V_{GS})}{qN_D}}$$

$$59. \quad V_{p0} = \frac{qa^2 N_d}{2\epsilon_s}$$

$$61. \quad V_{Dsat} = V_{p0} - (V_{bi} - V_{GS})$$

$$58. \quad I_D = I_P \left[3 \left(\frac{V_{DS}}{V_{p0}} \right) - 2 \left(\frac{V_{DS} + V_{bi} - V_{GS}}{V_{p0}} \right)^{3/2} + 2 \left(\frac{V_{bi} - V_{GS}}{V_{p0}} \right)^{3/2} \right]$$

$$60. \quad I_P = \frac{\mu_n (qN_d)^2 W a^3}{6\epsilon_s L}$$

$$62. \quad I_{Dsat} = I_P \left[1 - 3 \left(\frac{V_{bi} - V_{GS}}{V_{p0}} \right) \left(1 - \frac{2}{3} \sqrt{\frac{V_{bi} - V_{GS}}{V_{p0}}} \right) \right]$$

MESFET

$$63. \quad R = \frac{L}{q\mu_n N_D A}$$

$$65. \quad I_D = I_P \left[\frac{V_D}{V_p} - \frac{2}{3} \left(\frac{V_D + V_G + V_{bi}}{V_p} \right)^{3/2} + \frac{2}{3} \left(\frac{V_G + V_{bi}}{V_p} \right)^{3/2} \right]$$

$$67. \quad I_P = \frac{Z\mu_n q^2 N_D^2 a^3}{2\epsilon_s L}$$

$$69. \quad V_{Dsat} = \frac{qN_D a^2}{2\epsilon_s} - V_{bi} - V_G$$

$$71. \quad g_m = \frac{I_P V_D}{2V_{p0}^2} \sqrt{\frac{V_{p0}}{V_G + V_{bi}}}, \quad \text{lin}$$

$$64. \quad I_D = \frac{V_D}{R}$$

$$66. \quad V_{p0} = \frac{qa^2 N_d}{2\epsilon_s}$$

$$68. \quad I_{Dsat} = I_P \left[\frac{1}{3} - \left(\frac{V_G + V_{bi}}{V_{p0}} \right) + \frac{2}{3} \left(\frac{V_G + V_{bi}}{V_{p0}} \right)^{3/2} \right]$$

$$70. \quad V_B = V_D + |V_G|$$

$$72. \quad g_m = \frac{I_P}{V_{p0}} \left(1 - \sqrt{\frac{V_G + V_{bi}}{V_{p0}}} \right), \quad \text{sat}$$

MODFET

$$73. \quad V_{p0} = \frac{qa^2 N_d}{2\epsilon_s}$$

$$75. \quad I = \frac{Z}{L} \mu_n C_i (V_G - V_T) V_D$$

$$77. \quad I_{sat} = \frac{Z\mu_n \epsilon_s}{2L(d_1 + d_0 + \Delta d)} (V_G - V_T)^2$$

$$74. \quad V_T = \phi_{Bn} - \frac{\Delta E_C}{q} - V_{p0}$$

$$76. \quad V_{Dsat} = V_G - V_T$$

FINAL EXAMINATION

SEMESTER/SESSION : SEM II / 2018/2019

PROGRAMME : BEJ

COURSE NAME : ADVANCED SEMICONDUCTOR DEVICES

COURSE CODE : BED 41003

Table 4
List of formula (Cont..)

Thyristors

79. $V_B \approx 6.0 \times 10^{13} (N_{nl})^{-0.75}$

80. $V_{PT} = \frac{qN_{nl}W_{nl}^2}{2\epsilon_s}$

81. $V_{BR} = V_B (1 - \alpha_1)^{\frac{1}{n}}$

82. $\alpha_1 = \text{sech}\left(\frac{W}{L_{nl}}\right)$

83. $W = W_{nl} \left(1 - \sqrt{\frac{V_{AK}}{V_{PT}}}\right)$

84. $I_{C1} = \alpha I_E + I_{CO1}$

85. $I_{B1} = (1 - \alpha_1)I_A - I_{CO1}$

86. $I_{C2} = \alpha_2 I_K + I_{CO2}$

87. $I_A = \frac{\alpha_2 I_g + I_{CO1} + I_{CO2}}{1 - (\alpha_1 + \alpha_2)}$

88. $V_{BF} = V_B (1 - \alpha_1 - \alpha_2)^{1/n}$

89. $V_{AK} = V_1 - V_2 + V_3$

90. $J = \frac{qnW_i}{\tau_{eff}}$

91. $\tau_{eff} = \frac{1}{\left(2A_r n^2 + \frac{1}{\tau_{p0} + \tau_{n0}}\right)}$